

-30V P-Channel Enhancement Mode MOSFET

Description

The AP3407BI uses advanced Trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 10V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

$V_{DS} = -30V$ $I_D = -4.2A$

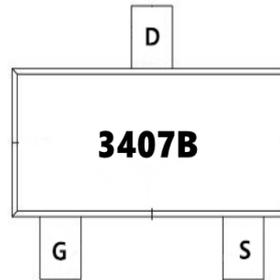
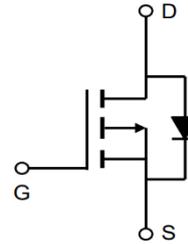
$R_{DS(ON)} < 55m\Omega$ @ $V_{GS}=10V$ (Type: **45m Ω**)

Application

Battery protection

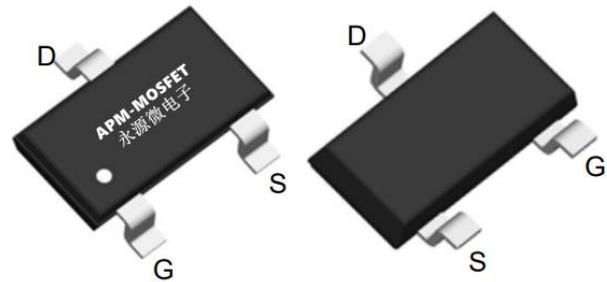
Load switch

Uninterruptible power supply



Top View

Bottom View



Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
AP3407BI	SOT23L	3407B-AP	3000

Absolute Maximum Ratings ($T_C=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Max.	Units
V_{DSS}	Drain-Source Voltage	-30	V
V_{GSS}	Gate-Source Voltage	± 20	V
$I_D @ T_C=25^\circ C$	Continuous Drain Current, $V_{GS} @ -10V^1$	-4.2	A
$I_D @ T_C=100^\circ C$	Continuous Drain Current, $V_{GS} @ -10V^1$	-2.6	A
IDM	Pulsed Drain Current ^{note1}	-16.8	A
P_D	Power Dissipation $T_A = 25^\circ C$	1	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	125	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance from Junction to Ambient ²	135	$^\circ C/W$
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to +150	$^\circ C$



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Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V(BR)DSS	Drain-Source Breakdown Voltage	V _{GS} = 0V, I _D = -250μA	-30	-	-	V
IDSS	Zero Gate Voltage Drain Current	V _{DS} = -30V, V _{GS} = 0V	-	-	-1	μA
IGSS	Gate-Source Leakage	V _{DS} = 0V, V _{GS} = ±20V	-	-	±100	nA
VGS(th)	Gate-Source Threshold voltage	V _{DS} = V _{GS} , I _D = -250μA	-1.2	-1.5	-2.5	V
RDS(on)	Drain-Source on-State Resistance ³	V _{GS} = -10V, I _D = -4A	-	45	58	mΩ
		V _{GS} = -4.5V, I _D = -3A	-	62	75	
Ciss	Input Capacitance	V _{GS} = 0V, V _{DS} = -15V, f = 1.0MHz	-	520	-	pF
Coss	Output Capacitance		-	70	-	
Crss	Reverse Transfer Capacitance		-	60	-	
Qg	Total Gate Charge	V _{GS} = -10V, V _{DS} = -15V, I _D = -4.1A	-	12	-	nC
Qgs	Gate-Source Charge		-	3	-	
Qgd	Gate-Drain Charge		-	2	-	
td(on)	Turn-on Delay Time	V _{GS} = -10V, V _{DS} = -15V , R _L = 15Ω,R _{GEN} = 2.5Ω	-	5	-	ns
t _r	Rise Time		-	28	-	
td(off)	Turn-off Delay time		-	30	-	
t _f	Fall Time		-	35	-	
VSD	Diode Forward Voltage ³	I _S = -4.1A, V _{GS} = 0V	-	-	-1.2	V
IS	Continuous Source Current		-	-	-4.1	A

Note :

- 1、 The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2、 The data tested by pulsed , pulse width ≅ 300us , duty cycle ≅ 2%
- 3、 The power dissipation is limited by 150°C junction temperature
- 4、 The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

Typical Characteristics

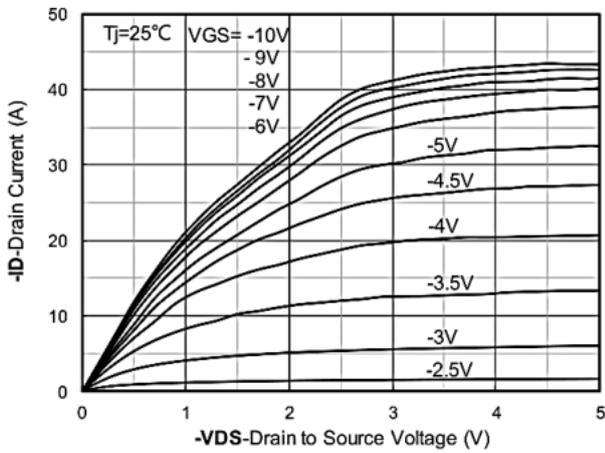


Figure 1. Output Characteristics

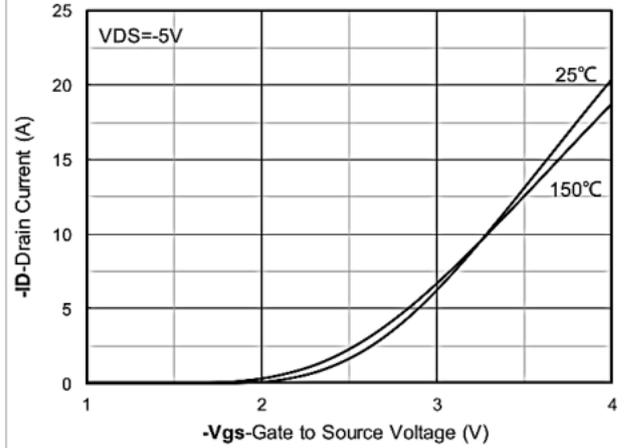


Figure 2. Transfer Characteristics

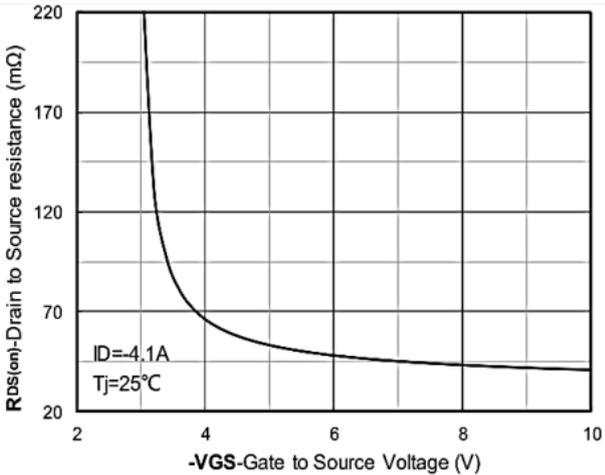


Figure 4. On-Resistance vs Gate to Source Voltage

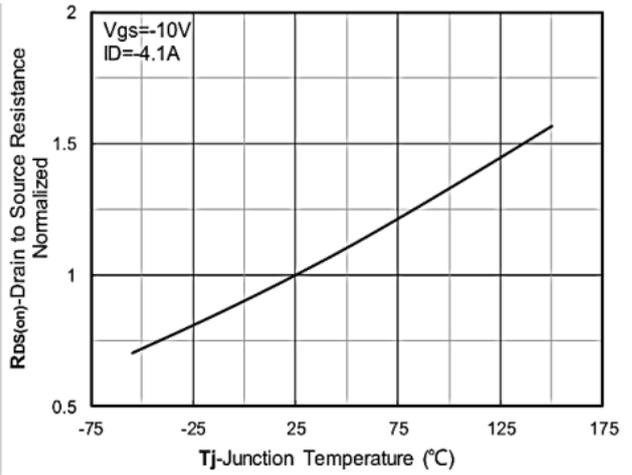


Figure 5. Normalized On-Resistance vs Junction Temperature

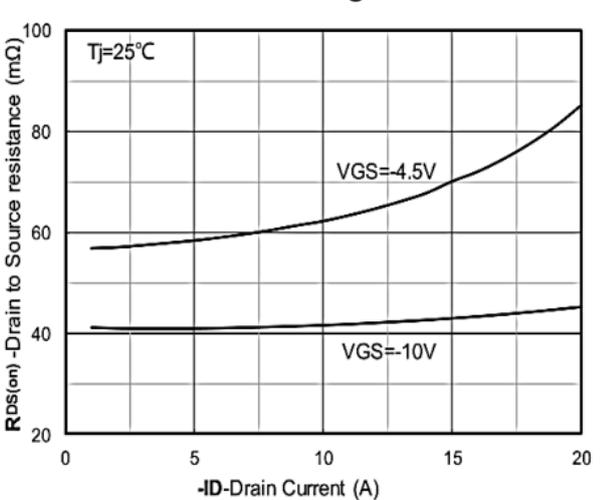


Figure 6. $R_{DS(on)}$ VS Drain Current

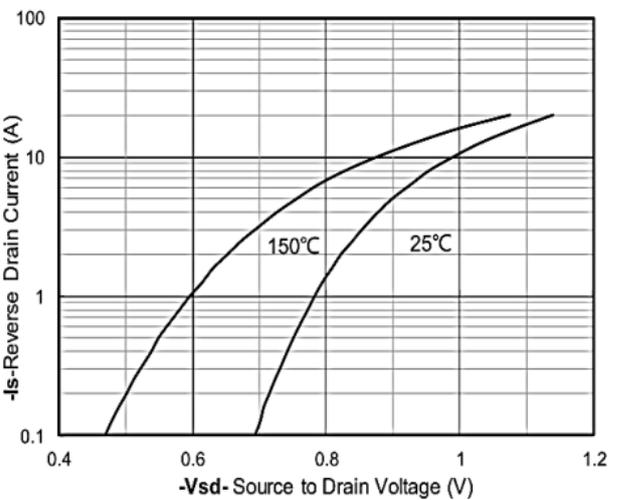


Figure 7. Forward characteristics of reverse diode



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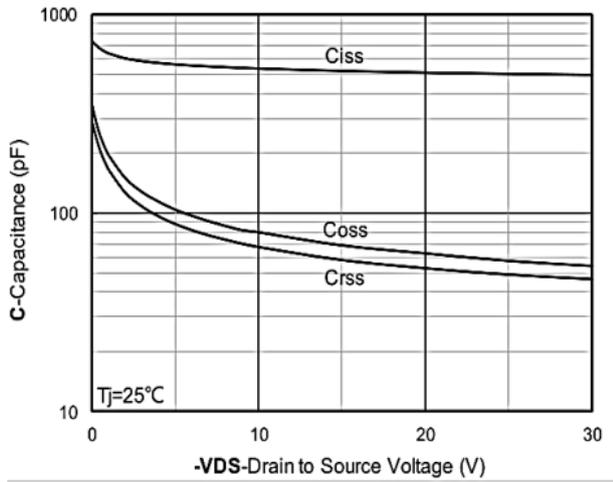


Figure 7. Capacitance Characteristics

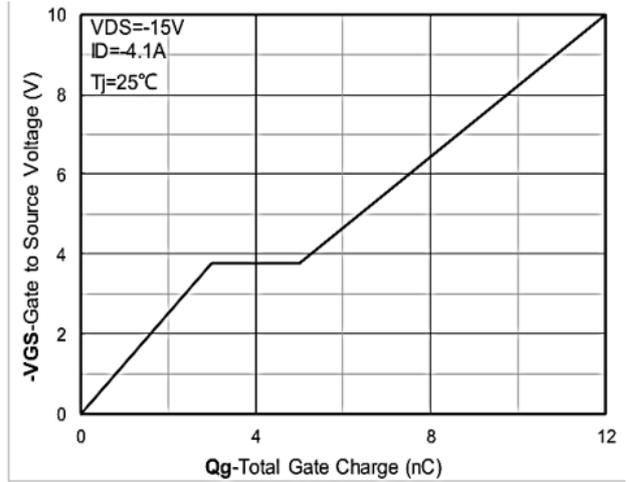


Figure 8. Gate Charge

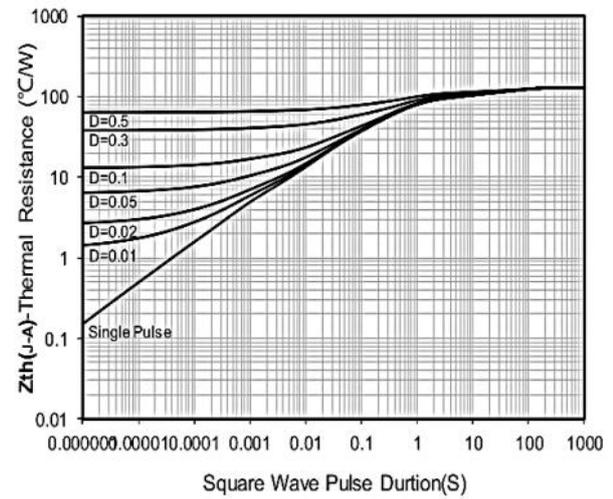


Figure 9. Maximum Transient Thermal Impedance

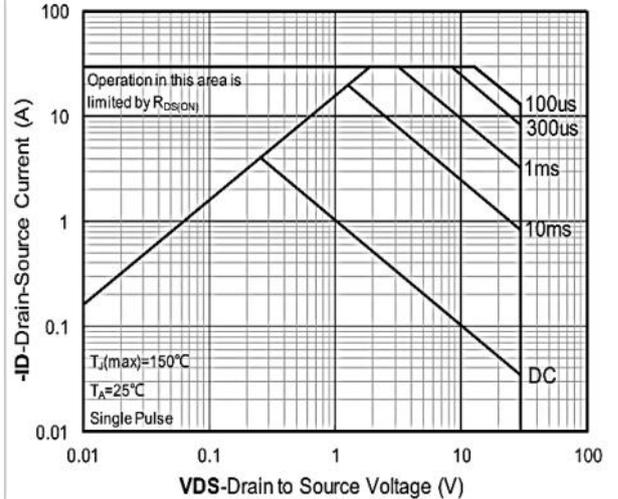
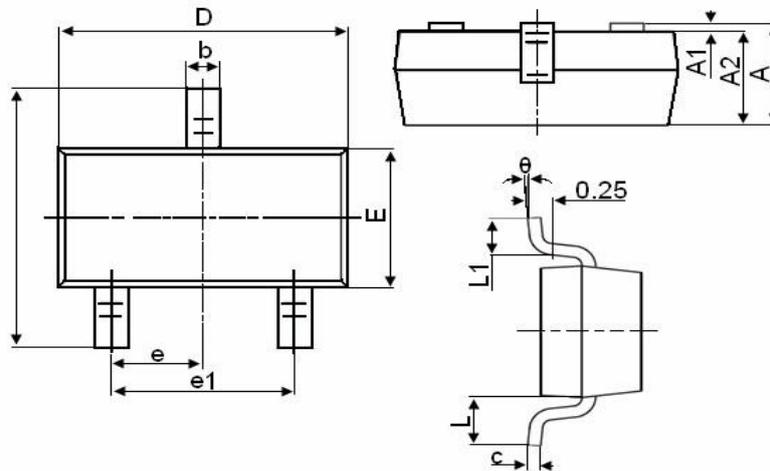


Figure 10. Safe Operation Area

Package Mechanical Data-SOT23-XC-Single



Symbol	Dimensions in Millimeters	
	MIN.	MAX.
A	0.900	1.150
A1	0.000	0.100
A2	0.900	1.050
b	0.300	0.500
c	0.080	0.150
D	2.800	3.000
E	1.200	1.400
E1	2.250	2.550
e	0.950TYP	
e1	1.800	2.000
L	0.550REF	
L1	0.300	0.500
θ	0°	8°

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Edition	Date	Change
Rve1.0	2022/8/31	Initial release

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